

HANDLING OF COMPONENTS AND SOLDERING TECHNIQUES

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12.0 HANDLING OF COMPONENTS AND SOLDERING TECHNIQUES

12.1 HANDLING OF COMPONENTS

12.1.1 Standard parts

Electrical and mechanical parts replacements can be obtained through your local PHILIPS organisation or representative. However, many of the standard electronic components can be obtained from other local suppliers. Before purchasing or ordering replacement parts, check chapter 15 "PARTS LISTS" for value, tolerance, rating and description.

NOTE: Physical size and shape of a component may affect instruments performance, particularly at high frequencies.
Always use direct replacement components, unless it is known that a substitute will not degrade the instruments performance.

12.1.2 Special parts

In addition to the standard electronic components, some special components are used:

- Components, manufactured or selected by PHILIPS to meet specific performance requirements.
- Components which are important for the safety of the instrument.

ATTENTION: Both type of components may only be replaced by components obtained through your local PHILIPS organisation or representative.

12.1.3 Transistors and integrated circuits

- Return transistors and I.C.'s to their original positions, if removed during routine maintenance.
- Do not renew or switch semi-conductor devices unnecessary, as it may affect the calibration of the instrument.
- Any replacement component should be of the original type or a direct replacement. Bend the leads to fit in the socket or pcb-holes and cut the leads to the same length as on the component being renewed.
- When a device has been renewed, check the operation of the part of the instrument, that may be affected.
- When re-installing power-supply transistors, use silicon grease to increase the heat-transfer capabilities.

WARNING: Handle silicon grease with care. Avoid contact with the eyes. Wash hands thoroughly after use.

12.1.4 Static sensitive components

This instrument contains electrical components that are susceptible to damage from static discharge. Servicing static-sensitive assemblies or components should be performed only at a static-free work station by qualified service personnel.

12.2 HANDLING OF MOS DEVICES

Though all our MOS integrated circuit incorporate protection against electrostatic discharges, they can nevertheless be damaged by accidental over-voltages. In storing and handling them, the following precautions are recommended.

CAUTION: Testing or handling and mounting call for special attention to personal safety. Personnel handling MOS devices should normally be connected to ground via a resistor.

12.2.1 Storage and transport

Store and transport the circuits in their original packing. Alternatively, use may be made of a conductive material or a special IC carrier that either short-circuits all leads or insulates them from external contact.

12.2.2 Testing or handling

Work on a conductive surface (e.g. metal table top) when testing the circuits or transferring them from one carrier to another. Electrically connect the person doing the testing or handling to the conductive surface, for example by a metal bracelet and a conductive cord to a chain. Connect all testing and handling equipment to the same surface. Signals should not be applied to the input while the device power supply is off. All unused input leads should be connected either to the supply voltage or to ground.

12.2.3 Mounting

Mount MOS integrated circuits on printed circuit boards after all other components have been mounted. Take care that the circuits themselves, metal parts of the board, mounting tools, and the person doing the mounting are kept at the same electric (ground) potential. If it is impossible to ground the printed-circuit board, the person mounting the circuit should touch the board before bringing the MOS circuits into contact with it.

12.2.4 Soldering

Soldering iron tips, including those of low voltage irons, or soldering baths should also be kept at the same potential as the MOS circuits and the board.

12.2.5 Static charges

Dress personnel in clothing of non-electrostatic material (no wool, silk or synthetic fibres). After the MOS circuits have been mounted, the proper handling precautions should still be observed.

Until the sub-assemblies are inserted into the complete system in which the proper voltages are supplied, the board is no more than an extension of the leads of the devices mounted on the board. To prevent static charges from being transmitted through the board wiring to the device it is recommended that conductive clips or conductive tape is put on the circuit board terminals.

12.2.6 Transient voltages

To prevent permanent damage due to transient voltages, do not insert or remove MOS devices, or printed circuit boards with MOS devices, from test sockets or systems with power on.

12.2.7 Voltage surges

Beware of voltage surges due to switching electrical equipment ON or OFF, relays and d.c. lines.

12.3 SOLDERING TECHNIQUES

Working method:

- Carefully unsolder one after the other the soldering tags of the semi-conductor.
- Remove all superfluous soldering material. Use a sucking iron or sucking litze wire.
- Check that the tags of the replacement part are clean and pre-tinned on the soldering places.
- Locate the replacement semi-conductor exactly on its place, and solder each tag to the relevant printed conductor on the circuit board.

NOTE: Bear in mind that the maximum permissible soldering time is 10 seconds during which the temperature of the tags must not exceed 250°C. The use of solder with a low melting point is therefore recommended.

Take care not to damage the plastic encapsulation of the semi-conductor (softening point of the plastic is 150°C).

ATTENTION: When you are soldering inside the instrument it is essential to use a low-voltage soldering iron, the tip of which must be earthed to the mass of the oscilloscope.

Suitable soldering irons are:

- ORYX micro-miniature soldering instrument, type 6 A, voltage 6 V, in combination with PLATO pin-point tip type 0-569.
- ERSA miniature soldering iron, type minor 040 B, voltage 6 V.
- Low voltage mini soldering iron, type 800/12 W-6 V, power 12 W, voltage 6 V, order no. 4822 395 10004, in combination with 1 mm pin-point tip, order no. 4822 395 10012.

Ordinary 60/40 solder with core and 35- to 40 W pencil type soldering iron can be used to accomplish the majority of the soldering. If a higher wattage-rating soldering iron is used on the etched circuit boards, excessive heat can cause the etched circuit wiring to separate from the board base material.

12.3.1. Soldering and desoldering of surface mounted devices

Introduction

This description gives you a method for replacing surface mounted devices (S.M.D.'s) and incorporates subjects such as:

- required tools and materials.
- how to arrange the S.M.D.-workshop. (see figure 12.1).
- general hints for S.M.D.-handling.
- interchanging S.M.D.'s with two or three connections.
- interchanging S.M.D.'s with four or more connections.

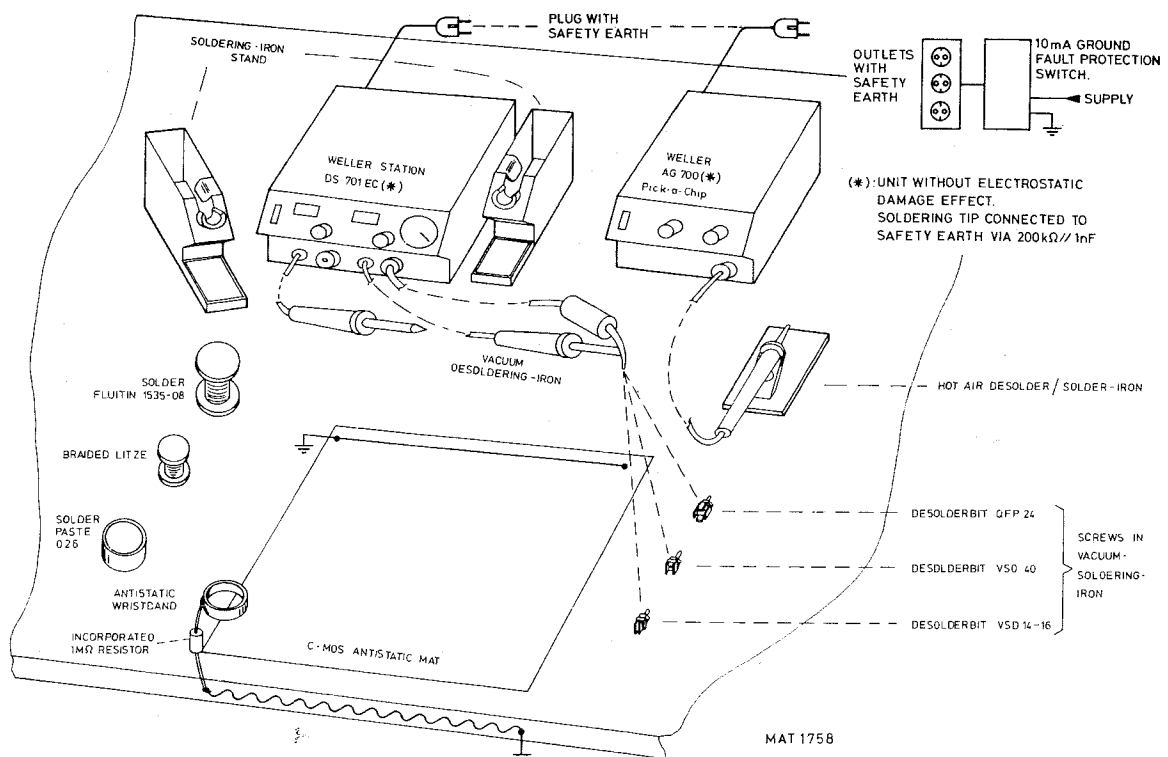


Figure 12.1 Arrangement of working area for S.M.D. exchange.

Required tools and materials

The following tools are necessary:

- A hot-air soldering/desoldering station for components with two or three leads: Weller AG 700 pick-a-chip.
- A vacuum, temperature controlled, soldering/desoldering station for components with four or more connections: Weller DS 701 EC.
- Desoldering accessories that can be attached to the Weller DS 701 EC-equipment: for dual-in-line S.M.D.'s VSO 14 and VSO 16 (with 14 and 16 connections such as used on the HF-attenuator p.c.b.) the types with Weller ordering code 587 13 701 and 587 13 702. For dual-in-line S.M.D.'s VSO 40 (with 40 connections such as used on the LCD-unit) the type with Weller ordering code 587 13 703. For QFP 24 S.M.D.'s (such as used on the time base chip unit) the type with Weller ordering code 587 13 704.
- A working area that has been secured against electro static discharge (E.S.D.).
- A pair of tweezers.

NOTE: The Weller equipment can be ordered via your local Weller-dealer.

The following material is necessary:

- "Fluittin" solder diameter of 0,8 mm, 15/35, Sn Pb 60.
- Solder paste 026.
- Components. Since not all the components are marked, they must be kept in their original packing in order to avoid interchanging them.
- Desoldering braided wire.

General hints for S.M.D.-mounting.

- Protection against E.S.D.: since the working area must be suitable for repair of MOS-devices, some precautions must be taken (see figure 12.1)
All repairs must be done earthened which means that the repair surface, the soldering iron and the technician must be connected to the earth potential. This is achieved by using a C-MOS antistatic mat that must be connected to earth. The service-technician is connected to earth by wearing an antistatic wristband.
- Components: desoldered components cannot be used again since desoldering is done at a temperature of 350 degrees Celcius while they can only withstand 240 degrees Celcius for max. 10 sec.
Keep the new components as long as possible in their original packing in order to avoid damage and mixing up new and old S.M.D.'s.
- For an optimal supply of heat a working area must be used that does not lead away the heat: the antistatic mat in figure 12.1 meets this requirement.

Interchanging S.M.D.'s with two or three connections.

IMPORTANT: Before removing the component, observe very carefully its position in order to avoid that the new component is installed upside-down. This is especially important for capacitors where the metallisation at both ends is longer at the p.c.b. side than at the top side.

Use the equipment Weller AG 700 pick-a-chip and proceed as follows:

- Heat the component up equably with hot air of 350 degrees Celcius.
- Remove the component with a pair of tweezers.
- Clean the p.c.b. tracks, on which the new component has to be soldered, with braided wire or with the use of the vacuum desoldering equipment DS 701 EC.
- Put solder paste on the connections of the new component and position it on the p.c.b..
- Solder the component on to the p.c.b. with the solder described in the materials list. Soldering temperature must be 240 degrees Celsius, soldering time must not exceed 3 sec. per connection. The tip of your soldering iron must not touch the component, but must touch the p.c.b. track close to the component.

Interchanging S.M.D.'s with four or more connections.

Use the equipment Weller DS 701 EC and attach a suitable desoldering piece (VS0 14, VS0 16, VS0 40 or OFP 24). Then proceed as follows:

- Adjust the desoldering temperature to 350 degrees Celcius and place the desoldering piece on the IC that has to be removed. Take care that all connections of the IC are equally heated up).
- Switch the vacuum on and lift the component from the p.c.b.
- Clean the p.c.b. tracks, on which the new component has to be soldered, with braided wire or with the use of the vacuum desoldering equipment DS 701 EC.
- Put solder paste on the connections of the new component and position it on the p.c.b.
- Position the component by soldering first the outside connections in a crosswise manner. Soldering temperature must be 240 degrees Celcius. Keep the soldering time as short as possible.
- Solder now the other connections.
- If necessary you must remove superfluous rests of solder with the use of braided wire.